

IN THE CLAIMS:

Please cancel claims 1-5 without prejudice or disclaimer of the subject matter thereof.

The following is a complete listing of claims in this application.

Claims 1-5 (canceled).

6. (currently amended) A method for manufacturing a light emitting diode device comprising the steps of:

preparing a body assembly ~~11~~ having a plurality of LED device areas formed by pressing a metal plate;

forming a recess in each of the LED areas;

forming slits in areas arranged on a predetermined line except both side edges;

charging a resin in each slit;

~~the wall of the~~ mounting an LED on a bottom of the recess by bumps;

charging a sealing resin under the LED;

securing a transparent sealing plate on the body assembly; and

dividing each area from the body assembly.

7. (new) The method according to claim 6 wherein the recess is formed into a semispherical shape.

8. (new) The method according to claim 6 wherein the recess is formed into an inverted truncated cone.

9. (new) The method according to claim 6 wherein the sealing plate is formed as a convex lens.